

A B C D

1 2 3 4 5 6

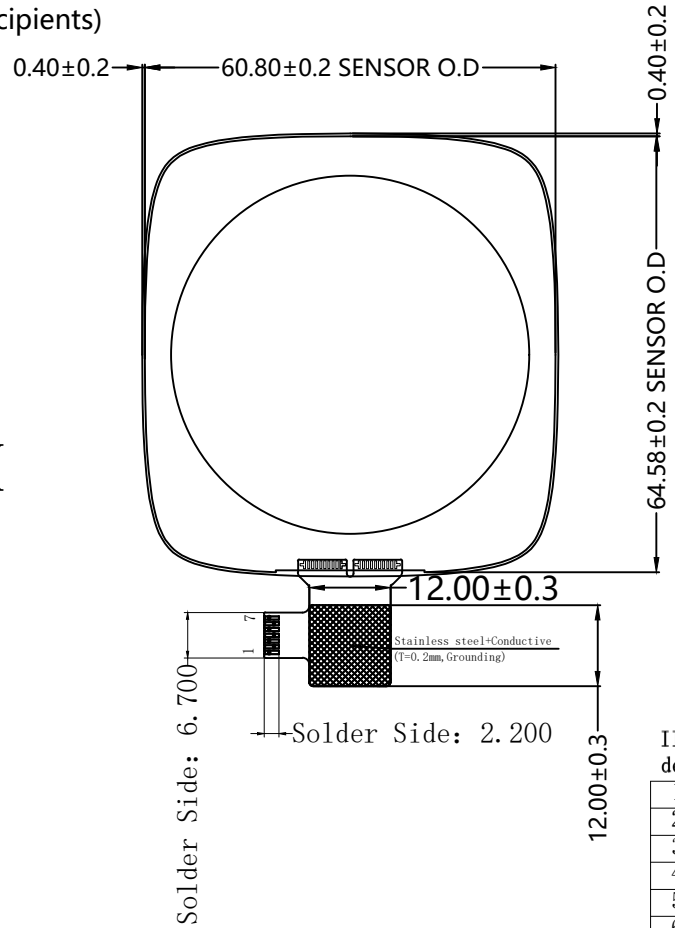
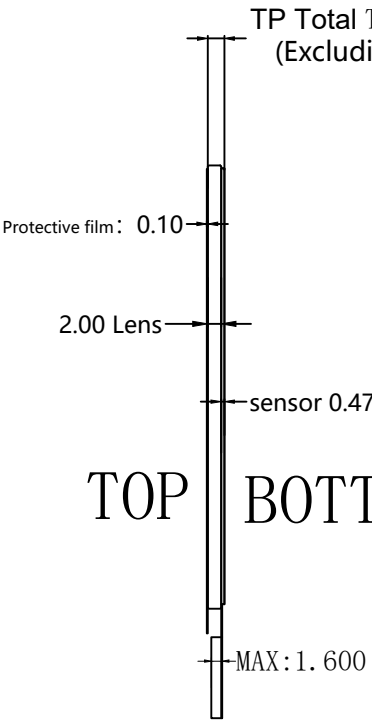
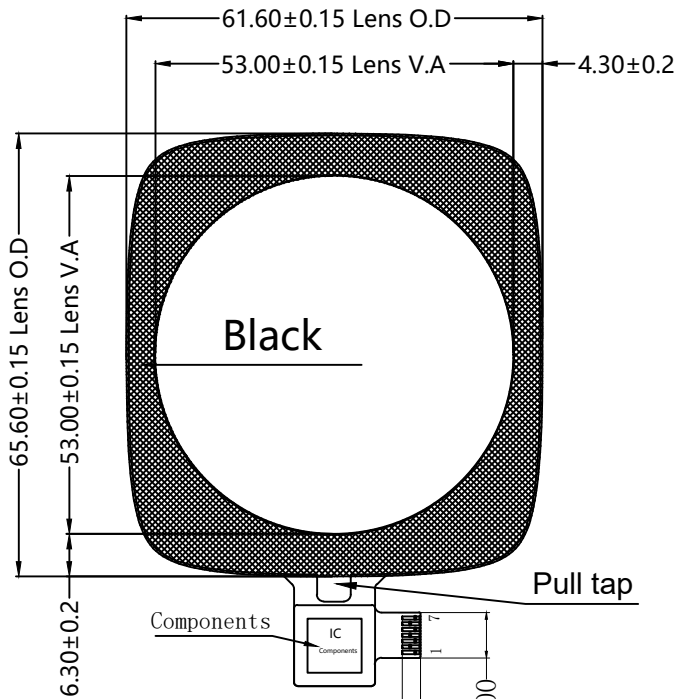
客户签名:

日期:

Front View

Side View

Back View



TOP BOTTOM
(G+FF Structure)

Technical Parameters:
1. GLASS+2*Film-ITO+FPC
2. COF: IC-FT3169, RX8*TX8
3. Glass Material: Asahi Glass
4. Glass Transparency: ≥85%
5. Glass Hardness: ≥6H
6. TP Working Environment:-20℃~+70℃, ≤90%RH
7. TP Storage Environment:-30℃~+80℃, ≤90%RH
8. ROHS Compliant
9. Unmarked Tolerance±0.2mm

Solder Side: 2.700

Solder Side: 6.700

Solder Side: 6.700

Solder Side: 2.200

IIC-TP logic definition:	
1	TP_VCC
2	TP_RESET
3	TP_VCC
4	TP_SCL
5	TP_SDA
6	TP_INT
7	GND

物料	NO.	更改内容	日期
	①		
	②		
	③		
	④		
	⑤		
	⑥		
	⑦		

工程确认图		
方向		
绘图	审核	日期

MAXEN ELECTRONICS LIMITED			
公司编号	HCT2501GFF024A1	未注公差	±0.20
客户编号	Squirrel_formed_glass with round visible area	单位	mm
版本号		比例	1 : 1

1 2 3 4 5 6

D C B A